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A review of porous lightweight composite materials for electromagnetic interference shielding

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Abstract

Lightweight porous materials for electromagnetic interference (EMI) shielding applications are reviewed. EMI shielding refers to the capability of a material to protect from electromagnetic fields (EMFs) generated by electronic devices. Traditionally conducting metals are used in EMI shielding applications, which are slowly being replaced by conducting polymer based shields. This review is narrowly focused on understanding the approaches related to porous high EMI shielding composite materials that have very low density values. While conducting fillers can

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